Fabrication of ISHELL Immersion Gratings

UT Si Diffraction Grating Group

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Principle of an immersion grating: (Fraunhofer 1823)

Infrared immersion gratings are an enabling technology because they can shrink instrument volumes by about an order of magnitude.



$$m\lambda = n_G \sigma(\sin \alpha + \sin \beta)$$
$$R_{\max} = \frac{2n_G L \sin \delta}{\lambda}$$
$$\frac{d\beta}{d\lambda} = \frac{2n_G \tan \beta}{\lambda}$$



By cutting the crystalline silicon at the right angle, we determine the blaze.



*Cutting angle depends on desired blaze angle $\boldsymbol{\delta}$



EHT = 10.00 kV WD = 10 mm

3µm

Mag = 17.65 K X

Signal A = InLens Date :12 Nov 2008

Time :15:48

Photo No. = 5721

The perfect shape and low roughness of etched grooves means low scattered light levels.





The high placement precision leads to high efficiency and spectral purity.



iShell grating G1 for NASA Infrared Telescope Facility





FORCAST grating G3 (mid/near IR camera for NASA's SOFIA airborne observatory)

JWST NIRCam grism A6-F

EHT = 10.00 kV Mag = 9.80 K X

6.16°, **15.36**μ

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Signal A = InLens Photo No. = 3177

Views of the CA1 (IGRINS Grating Completed Surface)

Images of CA1 post KOH etching, but before nitride stripping



Immersion Grating CA1, After Coating, August 2011





Grating along side a solid model mockup



View of the AR coated entrance face

Front-Surface Interferogram of CA1

Interferogram with a 25 mm beam, front surface at 632 nm Peak to Valley deviation is 0.16 waves 5nm repetitive error leads to 0.2% ghosts Measured efficiency in immersion:

Measured efficiency at 1.523 (close to the blaze but not on it) is 79 +/-6%

IGRINS Concept of the Instrument

IGRINS is a high resolution near-IR spectrograph:
R= 40,000
Slit 1"x 15" on the McDonald 2.7m, proportionally smaller on larger telescopes.
Stable and simple to use:
no moving parts

Very large spectral grasp (all of H and K at once) Good efficiency/sensitivity Slit viewing camera for efficient observations Pipeline reduction software for normal use.

University of Texas immersion grating process and development

UV patterning of photoresist

- The UV exposure system operates by moving the masksubstrate unit beneath a stationary UV light source.
- The exposed photoresist is then developed out in the wet processing bench in our main lab

Plasma etching of silicon nitride mask

- After patterning the photoresist, a silicon nitride layer is etched using a Trion Oracle inductively-coupled plasma (ICP) etch system.
- The interior of the etch chamber has a custom cathode cover manufactured to hold our thick silicon disks

Etching grating into silicon

- The grating surfaces are etched into silicon using a solution containing potassium hydroxide (KOH). The silicon nitride film previously etched asks as a hard mask during the silicon etching.
- The KOH setup includes a circulating chiller for temperature control of the ultrasonic batch in which the KOH etching solution is immersed

Metrology during processing

- A number of instruments are used for *in situ* process monitoring
- Non-destructive film thickness is measured using a Woollam ellipsometer and feature profile is measured using a Dektak profiler

Electron microscopy

- The TMI houses a Quanta environmental scanning electron microscope
- This SEM has a large sample chamber so that we can place the entire thick silicon substrates in the chamber allowing us to nondestructively image the gratings.

Optical interferometry

- We have recently purchased a Fizeau-type laser interferometer manufactured by Zygo corporation that is housed in the CNM
- This tool creates an optical interferogram that we use to characterize the quality of the grating after patterning is completed.

Efficiency characterization

- The efficiency measurement setup is located in our main lab
- This measurement compares the signal from the immersion grating to that of an aluminum mirror

ISHELL Requires two immersion gratings:

Long wave: (2.7-5.4 microns): 80 micron period Short wave: (1.15-2.5 microns) 48.5 micron perid

Both are R3 with a 30.5x35 mm entrance face.

The plan is to fabricate the long wavelength grating using contact lithography (a la CA1) but to fabricate the short wavelength grating using e-beam lithography with the JEOL writer at JPL.

ISHELL JHK Part: E-beam trial SEM images after etching

Residue is from undercut of nitride mask; part has not been cleaned yet.

Left-right asymmetry due to slight tilt on SEM.

Interferogram of E03 30mm thick piece for ISHELL L&M grating. This is a 30mm diameter aperture at 633 nm. This is about lamda/3 p to v in immersion at 4 microns on a 25mm aperture.

ISHELL possible grating

Same piece (G03) at a slightly different position. This realization would be lambda/4 over a 30mm aperture but note that the entrance face cannot be that perfect all the way to the edge.

Status and plans:

L&M: We have a marginally acceptable surface now. We are making tests now to our setup to understand the origin of the large-scale errors. This will involve sacrificing a 30mm thick part. After that, we should be able to re-make the part.

JHK: Has been in recovery from the destruction of a 100 hour write ISHELL part last year. We now understand the process issues that caused this and the groove samples you see demonstrate that we can safely write a thick part. The one issue remaining is to test this sample for ghosts.

Expect to write both types of parts in the next 2-3 months.